

GSMDD0903DF

100V P-Channel MOSFETs

Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

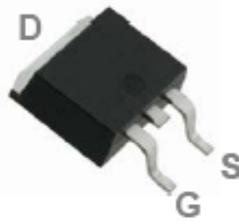
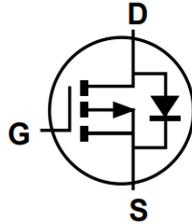
Features

- -100V, -10A, $R_{DS(ON)}=140m\Omega@V_{GS}=-10V$
- V_{GS} Guaranteed $\pm 25V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- TO-252-2L package design

Applications

- Networking
- Load Switch
- LED applications

Packages & Pin Assignments

TO-252-2L		Equivalent Circuit
 <p>Top View</p>		
Pin	Description	
1	Gate	
2	Source	
3	Drain	

Ordering and Marking Information

Ordering Information			
Part Number	Package	Part Marking	Quantity / Reel
GSMDD0903DF	TO-252-2L	DD0903 □□□□□□	2,500 PCS
GSMDD0903 1 2 - Product Code: GSMDD0903 - Package Code: 1 is D for TO-252-2L - Green Level: 2 is F for RoHS Compliant and Halogen Free			
Marking Information			
<div style="border: 1px solid black; padding: 5px; display: inline-block; text-align: center;"> DD0903 □□□□□□ </div> - Product Code: DD0903 - GS Code: □□□□□□			

Absolute Maximum Ratings (T_C=25°C Unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{DS}	Drain-Source Voltage	-100	V
V _{GS}	Gate –Source Voltage	±25	V
I _D	Continuous Drain Current	T _C =25°C	-10
		T _C =100°C	-6.5
I _{DM}	Pulsed Drain Current	-40	A
P _D	Power Dissipation (T _C =25°C)	73.5	W
	Power Dissipation (Derate above 25°C)	0.59	W/°C
T _J	Operating Junction Temperature Range	-55 to +150	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C
R _{θJA}	Thermal Resistance-Junction to Ambient	62	°C/W
R _{θJC}	Thermal Resistance-Junction to Case	1.7	°C/W

Electrical Characteristics (T_J=25°C Unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-100			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	-1		-3	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±25V			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-100V, V _{GS} =0V			-1	uA
		V _{DS} =-80V, V _{GS} =0V, T _J =125°C			-10	
I _S	Continuous Source Current	V _G =V _D =0V, Force Current			-10	A
I _{SM}	Pulsed Source Current				-20	
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =-10V, I _D =-6A		115	140	mΩ
		V _{GS} =-4.5V, I _D =-3A		130	170	mΩ
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-1A			-1.2	V
Dynamic						
Q _g	Total Gate Charge	V _{DS} =-50V, V _{GS} =-10V, I _D =-6A		40.4	70	nC
Q _{gs}	Gate-Source Charge			7.7	15	
Q _{gd}	Gate-Drain Charge			6.6	13	
C _{iss}	Input Capacitance	V _{DS} =-30V, V _{GS} =0V, f=1MHz		2250	3900	pF
C _{oss}	Output Capacitance			130	250	
C _{rss}	Reverse Transfer Capacitance			90	180	
t _{d(on)}	Turn-On Time	V _{DD} =-30V, I _D =-1A, V _{GS} =-10V, R _G =6Ω		27	54	ns
t _r				12	24	
t _{d(off)}	Turn-Off Time			150	300	
t _f				45	90	
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz		10		Ω

Typical Performance Characteristics

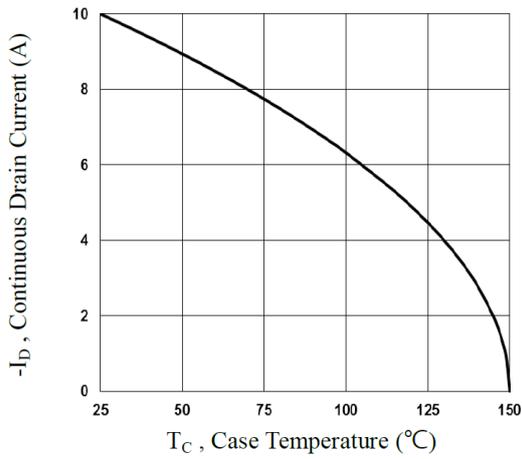


Fig.1 Continuous Drain Current vs. T_c

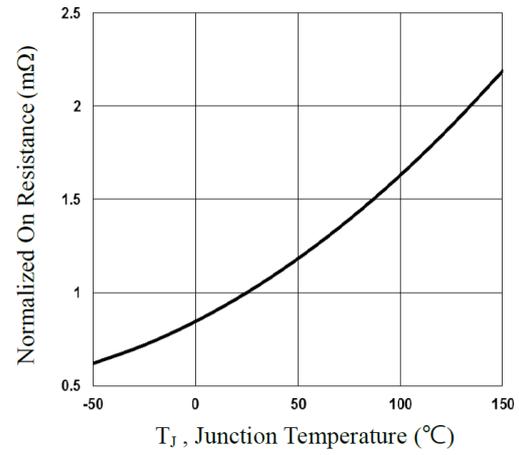


Fig.2 Normalized R_{DSON} vs. T_J

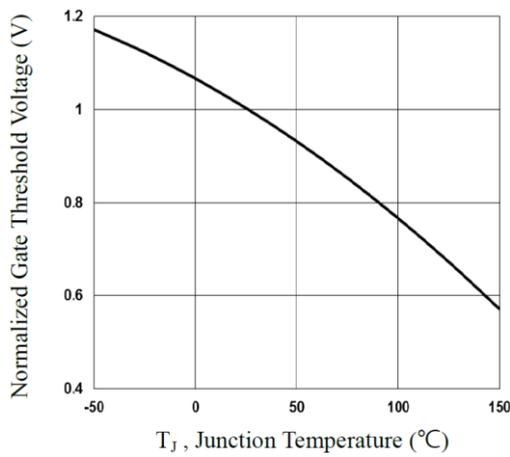


Fig.3 Normalized V_{th} vs. T_J

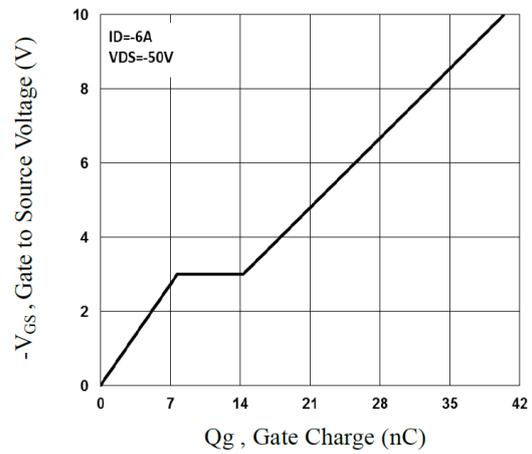


Fig.4 Gate Charge Waveform

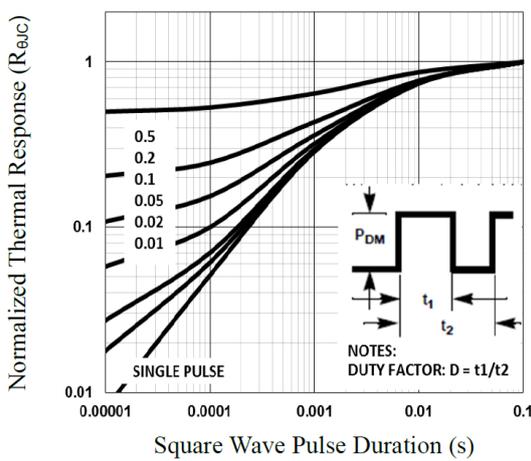


Fig.5 Normalized Transient Impedance

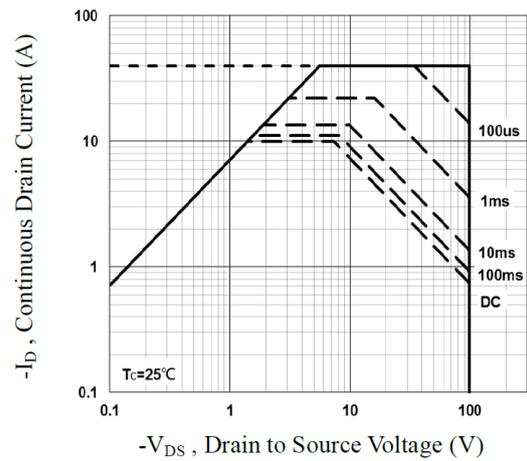
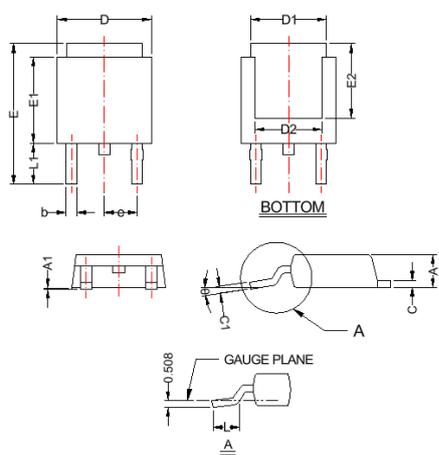


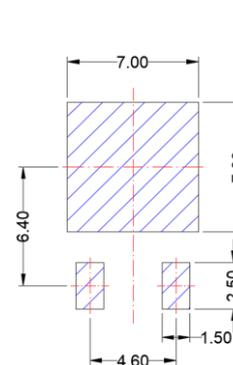
Fig.6 Maximum Safe Operation Area

TO-252-2L

Package Dimension



Recommended Land Pattern



(Appearance)

Unit:mm

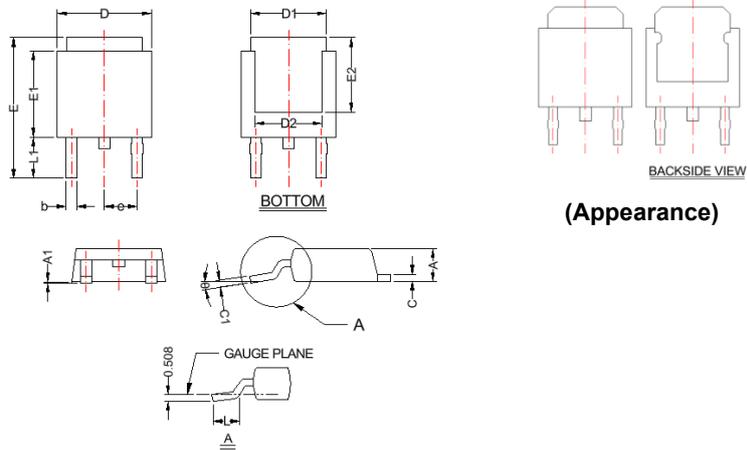
Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	2.18	2.40	0.086	0.094
A1	0.00	0.15	0.000	0.006
b	0.64	0.90	0.025	0.035
c	0.40	0.89	0.016	0.035
c1	0.40	0.61	0.016	0.024
D	6.35	6.73	0.250	0.265
D1	4.95	5.46	0.195	0.215
D2	4.32	---	0.170	---
E	9.40	10.41	0.370	0.410
E1	5.97	6.22	0.235	0.245
E2	4.95	---	0.195	---
e	2.286 BSC		0.090 BSC	
L	1.40	1.77	0.055	0.070
L1	2.67	3.07	0.105	0.121
θ	0°	8°	0°	8°

NOTE:

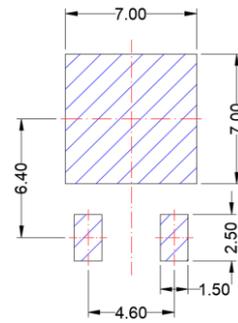
Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.

TO-252-2L

Package Dimension



Recommended Land Pattern



Unit:mm

Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	2.18	2.40	0.086	0.094
A1	0.00	0.15	0.000	0.006
b	0.50	0.90	0.020	0.035
c	0.45	0.89	0.018	0.035
c1	0.40	0.61	0.016	0.024
D	6.35	6.80	0.250	0.268
D1	4.95	5.50	0.195	0.217
D2	3.81	---	0.150	---
E	9.40	10.41	0.370	0.410
E1	5.33	5.80	0.210	0.228
E2	4.57	---	0.180	---
e	2.286 BSC		0.090 BSC	
L	1.40	1.78	0.055	0.070
L1	2.40	3.00	0.094	0.118
θ	0°	8°	0°	8°

NOTE:

Dimensions are exclusive of Burrs, Mold Flash and Tie Bar extrusions.

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